

AREA OF INTEREST

Papers in the following areas are invited by the symposium, but papers in other related areas will also be considered:

- Abrasive machining
- Abrasive jet machining
- Advanced cutting technology
- Beam processing and related topics
- CMP and semiconductor wafer processing
- Applications of abrasive technologies
- Eco-machining
- EDM and non-traditional machining
- Ultrasonic machining
- Finishing, lapping, polishing, and deburring
- Die, mold and related topics
- Grinding wheel and abrasive grain technologies
- High-speed and high-efficiency machining
- In-process measurement, monitoring, and metrology
- Machine tools and systems, tooling
- Additive manufacturing and related topics
- Micro/nano-machining
- Surface integrity and materials characterization
- Tribology in manufacturing
- Truing, dressing and ELID
- Smart Manufacturing Technology

REGISTRATION

Early-bird registration by Aug 15	
Full registration	USD 550
Student registration	USD 400
Late and onsite registration (after Aug 16)	
Full registration	USD 650
Student registration	USD 450

A registration for on-site attendance covers the costs for conference proceedings, welcoming reception, banquet, morning and afternoon refreshments, attendance to all the technical sessions, and lunches.

ISAAT 2023 HISTORY & SCOPE

The International Symposium on Advances in Abrasive Technology (ISAAT) was first held in Sydney, Australia in 1997. Since 2002, ICAT has been a driving force for the organization of this exciting annual event. This series of symposia has been successfully held in Hong Kong, China, UK, Turkey, Russia, US, Japan, Australia, Taiwan, China, Germany, Singapore, Mainland China, Republic of Korea, Sweden and Canada. An emphasis of the ISAAT series is to bring together both academic researchers and industrial practitioners from around the world for the interchange of the latest developments and applications in abrasive technologies. ISAAT2023 in Taichung, Taiwan, China will continue to promote the discipline development and research collaboration, and to foster the growth of young engineers and researchers in this field.

SYMPOSIUM ORGANIZATIONS

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IMPORTANT DATES

Date	Content
March 1	Full paper submission to both IJAT and ISAAT
May 1	Abstract submission to ISAAT
May 31	Full paper submission to ISAAT
June 30	Notification of ISAAT paper acceptance
July 31	Submission of final ISAAT paper
Aug.15	End of early registration fee
Dec. 10	Conference registration and reception
Dec.11-12	Technical sessions
Dec.13	Technical visit (optional)

SUBMISSION GUIDELINE

- Authors will be provided the options to submit their papers to ISAAT proceedings only, or to both ISAAT proceedings and the International Journal of Abrasive Technology (IJAT, EI indexed).
- The submission of a paper abstract is not required.
- Full ISAAT papers must be written in English from 4-6 proceedings pages.
- Each ISAAT paper must be formatted and submitted according to the Instructions for Authors available in the conference website.
- The version of the paper submitted to the IJAT has no limit.

PAPER PRESENTATION & PUBLICATION

All papers will be peer reviewed. Accepted papers MUST be presented in oral or poster session. Each delegate may present up to two papers (a publication fee will be charged for the second paper).

ACCOMMODATION

Information of hotel will be available on the conference website

SYMPOSIUM SECRETARIAT

Prof. Kai-Jung Chen Email: isaat2023@gmail.com

For conference details, updates and downloadable documents, visit the conference website at:

<https://im.ncut.edu.tw/p/426-1004-5.php>

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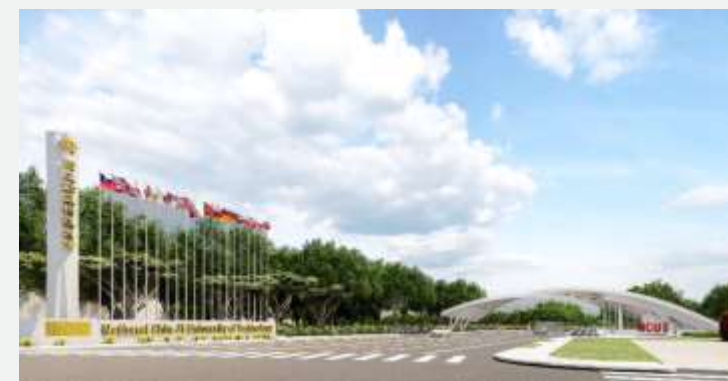
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Call for Papers

ISAAT 2023

The 25th International Symposium on
Advances in Abrasive Technology
10–13 December 2023
Taichung, Taiwan, China



Supported by

Taiwan Society of Abrasive Technology (TSAT)
International Committee for Abrasive Technology (ICAT)
The Japan Society for Abrasive Technology (JSAT)
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